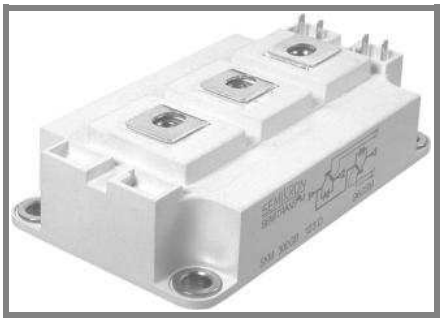
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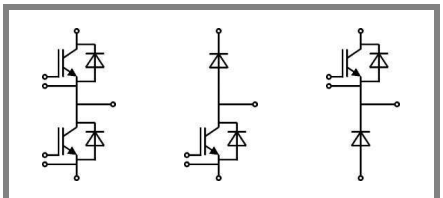
SKM 300GB063D
SKM 300GAR063D
SKM 300GAL063D

Features

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- Low tail current with low temperature dependence
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Typical Applications*

- Switching (not for linear use)
- Switched mode power supplies
- AC inverter servo drives
- UPS uninterruptable power supplies
- Welding inverters



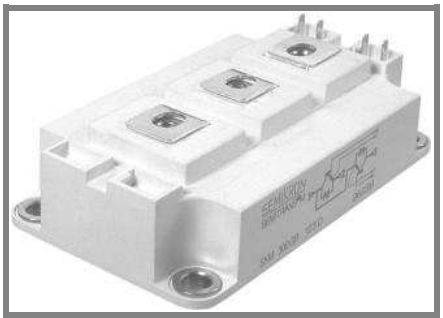
GB **GAL** **GAR**

Absolute Maximum Ratings			T_c = 25 °C, unless otherwise specified	
Symbol	**Conditions**		**Values**	**Units**
IGBT				
V_{CES}	T_j = 25 °C		600	V
I_C	T_j = 150 °C	T_{case} = 25 °C	400	A
		T_{case} = 70 °C	300	A
I_{CRM}	I_{CRM}=2xI_{Cnom}		600	A
V_{GES}			± 20	V
t_{psc}	V_{CC} = 300 V; $V_{GE} \leq$ 20 V; V_{CES} < 600 V	T_j = 125 °C	10	µs
Inverse Diode				
I_F	T_j = 150 °C	T_{case} = 25 °C	250	A
		T_{case} = 80 °C	170	A
I_{FRM}	I_{FRM}=2xI_{Fnom}		600	A
I_{FSM}	t_p = 10 ms; sin.	T_j = 150 °C	1600	A
Freewheeling Diode				
I_F	T_j = 150 °C	T_c = 25 °C	400	A
		T_c = 80 °C	270	A
I_{FRM}	I_{FRM}=2xI_{Fnom}		800	A
I_{FSM}	t_p = 10 ms; sin.	T_j = 150 °C	2800	A
Module				
$I_{t(RMS)}$			500	A
T_{vj}			- 40 ... + 150	°C
T_{stg}			- 40 ... + 125	°C
V_{isol}	AC, 1 min.		2500	V

Characteristics			T_c = 25 °C, unless otherwise specified			
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Units**
IGBT						
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 6 mA		4,5	5,5	6,5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = V_{CES}	T_j = 25 °C		0,2	0,6	mA
V_{CE0}		T_j = 25 °C		1,05		V
		T_j = 125 °C		1		V
r_{CE}	V_{GE} = 15 V	T_j = 25°C		3,2		mΩ
		T_j = 125°C		4,7		mΩ
$V_{CE(sat)}$	I_{Cnom} = 300 A, V_{GE} = 15 V	T_j = 25°C$_{chiplev.}$		2,1	2,5	V
		T_j = 125°C$_{chiplev.}$		2,4	2,8	V
C_{ies}	V_{CE} = 25, V_{GE} = 0 V	f = 1 MHz		17		nF
C_{oes}				2		nF
C_{res}				1,2		nF
Q_G	V_{GE} = 0V...+15V			720		nC
R_{Gint}	T_j = °C			0		Ω
$t_{d(on)}$	R_{Gon} = 6 Ω	V_{CC} = 300V		160		ns
t_r		I_C= 300A		80		ns
E_{on}		T_j = 125 °C		14		mJ
$t_{d(off)}$	R_{Goff} = 6 Ω	V_{GE} = ± 15V		550		ns
t_f				50		ns
E_{off}				13		mJ
$R_{th(j-c)}$	per IGBT				0,09	K/W

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Superfast IGBT Modules

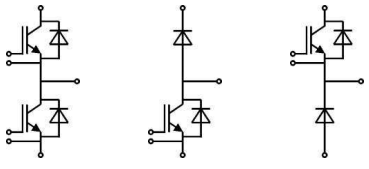
SKM 300GB063D
SKM 300GAR063D
SKM 300GAL063D

Features

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GB GAL GAR

Characteristics

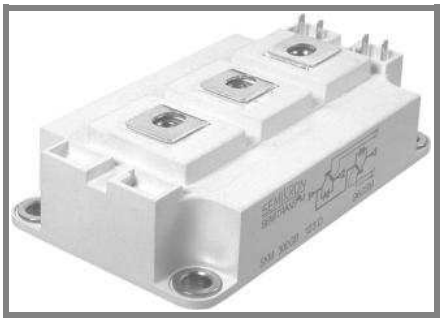
Symbol	Conditions		min.	typ.	max.	Units
Inverse Diode						
$V_F = V_{EC}$	I_{Fnom} = 300 A; V_{GE} = 0 V	T_j = 25 °C$_{chiplev.}$		1,65	2	V
		T_j = 125 °C$_{chiplev.}$		1,65	2	V
V_{F0}		T_j = 125 °C			0,9	V
r_F		T_j = 125 °C		3	3,7	mΩ
I_{RRM}	I_F = 300 A	T_j = 125 °C		120		A
Q_{rr}				18		µC
E_{rr}	V_{GE} = -15 V; V_{CC} = 300 V					mJ
$R_{th(j-c)D}$	per diode				0,25	K/W
Freewheeling Diode						
$V_F = V_{EC}$	I_{Fnom} = 400 A; V_{GE} = 0 V	T_j = 25 °C$_{chiplev.}$		1,65	2	V
		T_j = 125 °C$_{chiplev.}$		1,65	2	V
V_{F0}		T_j = 125 °C			0,9	V
r_F		T_j = 125 °C			3	V
I_{RRM}	I_F = 300 A	T_j = 125 °C		130		A
Q_{rr}				23		µC
E_{rr}	V_{GE} = -15 V; V_{CC} = 300 V					mJ
$R_{th(j-c)FD}$	per diode				0,15	K/W
Module						
L_{CE}				15	20	nH
$R_{CC'+EE'}$	res., terminal-chip	T_{case}= 25 °C		0,35		mΩ
		T_{case}= 125 °C		0,5		mΩ
$R_{th(c-s)}$	per module				0,038	K/W
M_s	to heat sink M6		3		5	Nm
M_t	to terminals M6		2,5		5	Nm
w					325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

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Superfast IGBT Modules

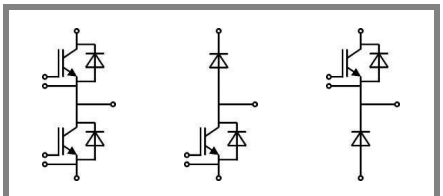
SKM 300GB063D
SKM 300GAR063D
SKM 300GAL063D

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GB **GAL** **GAR**

Z_{th} Symbol	Conditions	Values	Units
$Z_{th(j-c)I}$			
R_i	i = 1	65	mk/W
R_i	i = 2	19	mk/W
R_i	i = 3	4,7	mk/W
R_i	i = 4	1,3	mk/W
tau_i	i = 1	0,0518	s
tau_i	i = 2	0,0241	s
tau_i	i = 3	0,0021	s
tau_i	i = 4	0,0001	s
$Z_{th(j-c)D}$			
R_i	i = 1	140	mk/W
R_i	i = 2	85	mk/W
R_i	i = 3	20,55	mk/W
R_i	i = 4	4,45	mk/W
tau_i	i = 1	0,0613	s
tau_i	i = 2	0,0041	s
tau_i	i = 3	0,0045	s
tau_i	i = 4	0,0003	s

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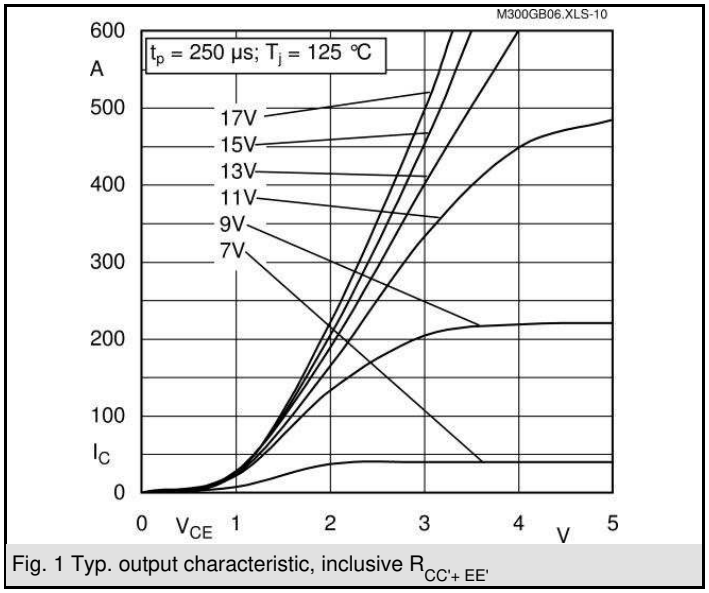


Fig. 1 Typ. output characteristic, inclusive $R_{CC'+EE'}$

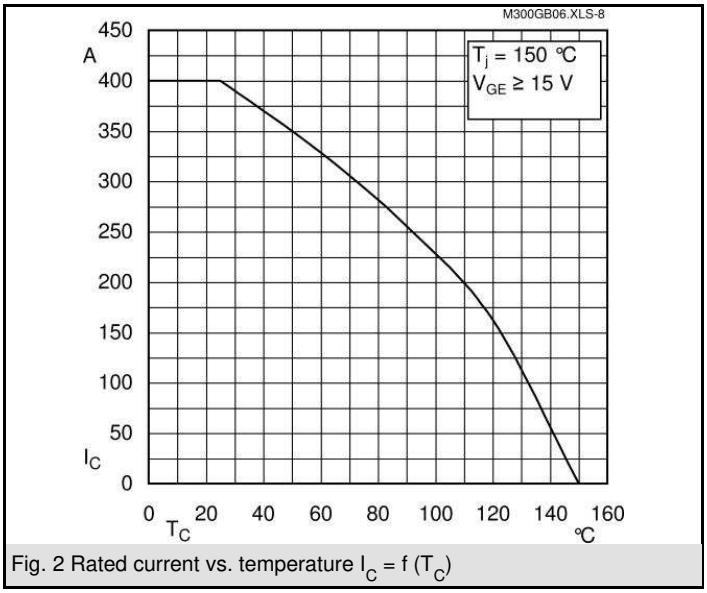


Fig. 2 Rated current vs. temperature $I_C = f(T_C)$

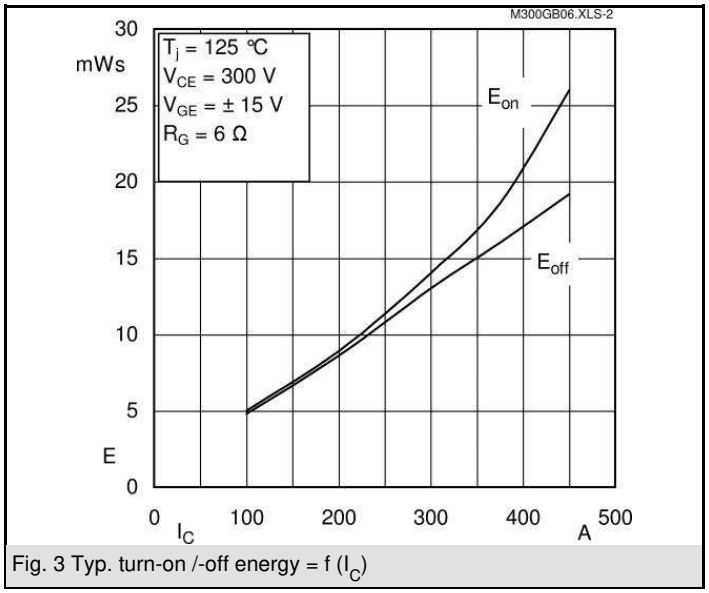


Fig. 3 Typ. turn-on /-off energy = f (I_C)

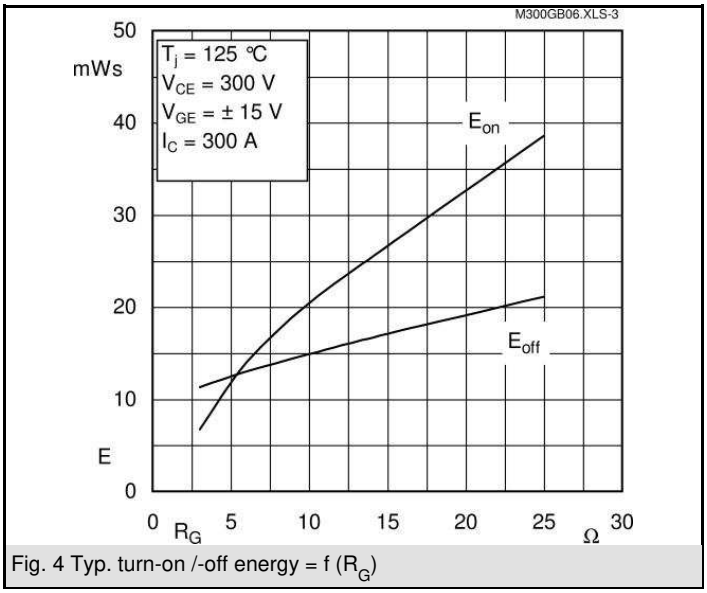


Fig. 4 Typ. turn-on /-off energy = f (R_G)

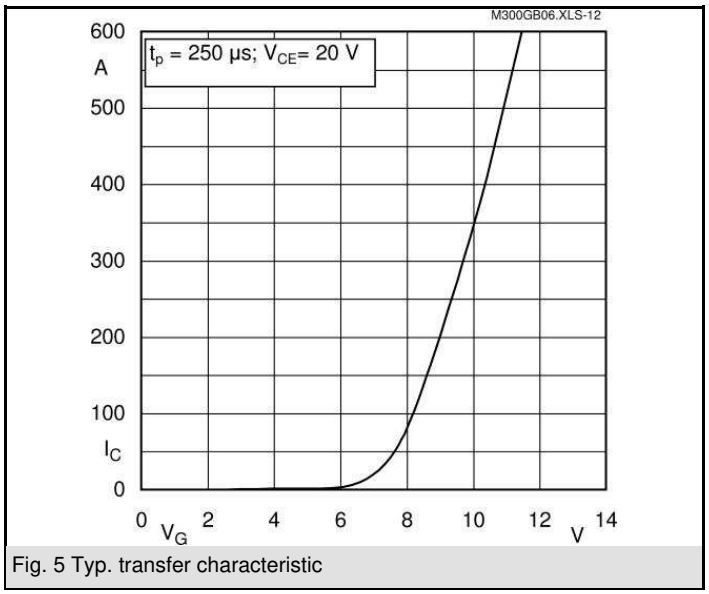


Fig. 5 Typ. transfer characteristic

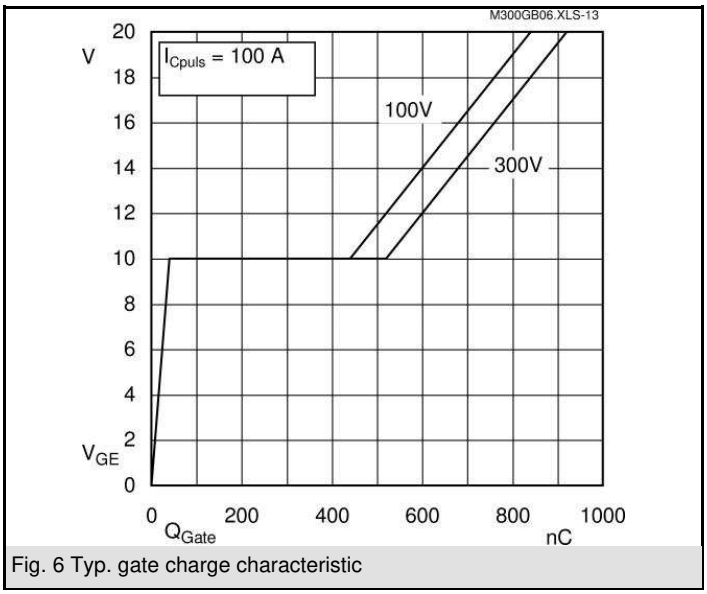


Fig. 6 Typ. gate charge characteristic

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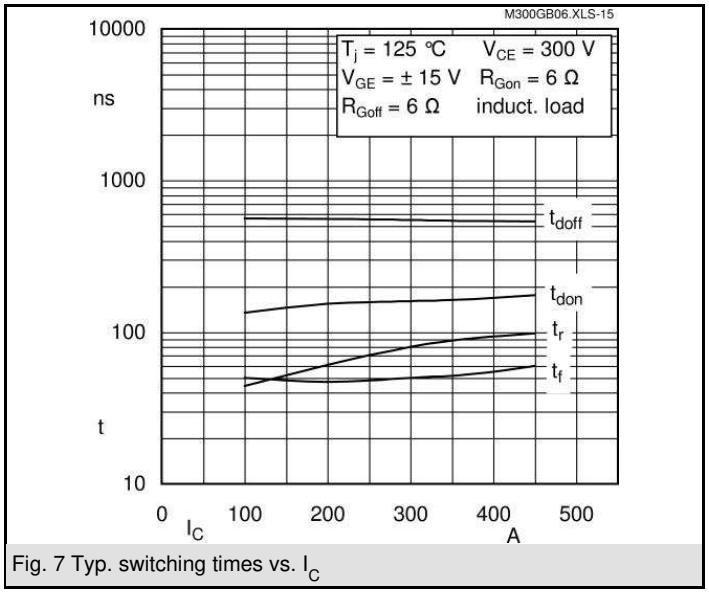


Fig. 7 Typ. switching times vs. I_C

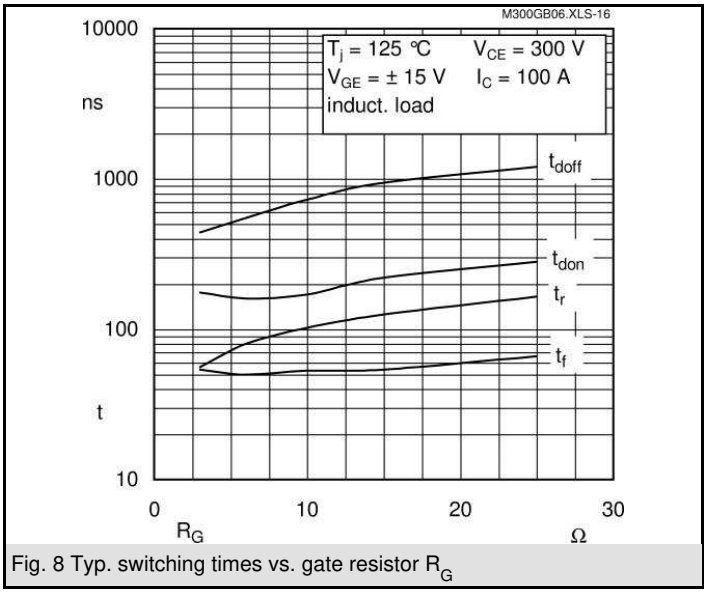


Fig. 8 Typ. switching times vs. gate resistor R_G

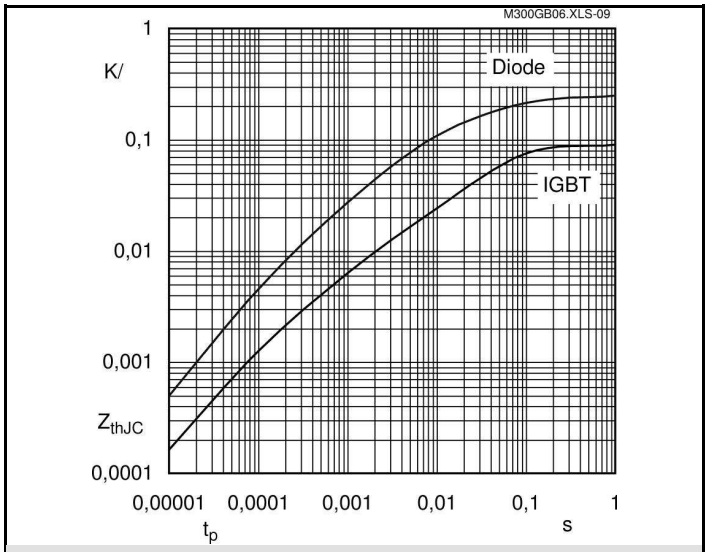


Fig. 9 Transient thermal impedance of IGBT and Diode

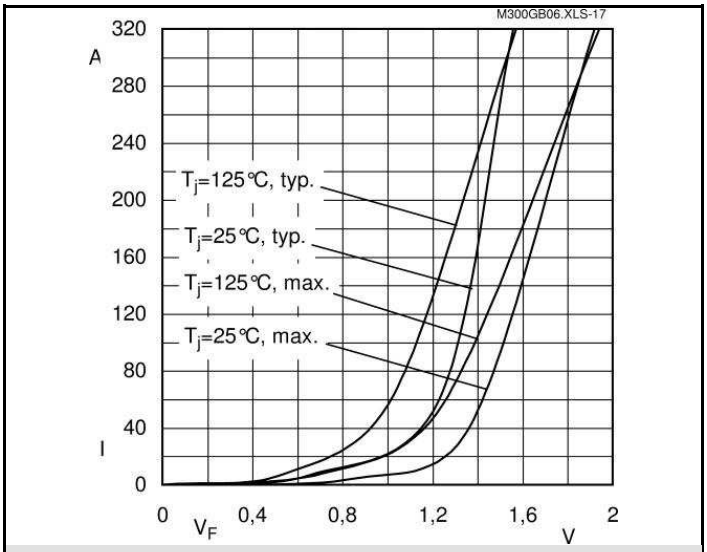


Fig. 10 CAL diode forward characteristic, inclusive $R_{CC'+ EE'}$

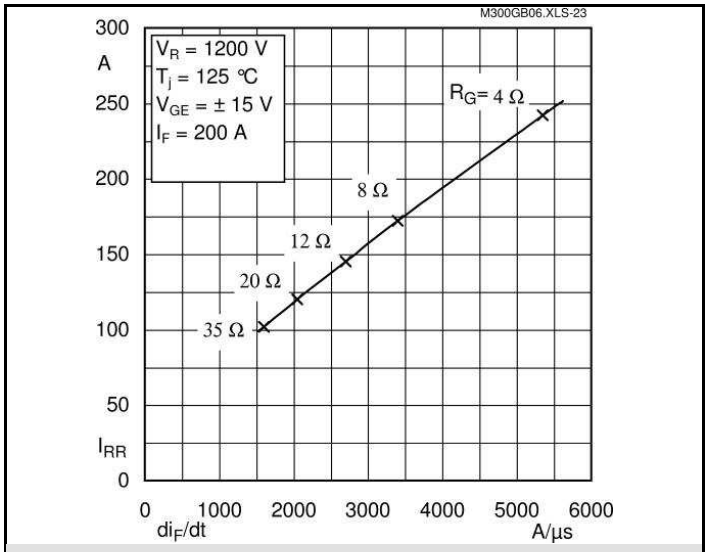


Fig. 11 Typ. CAL diode peak reverse recovery current

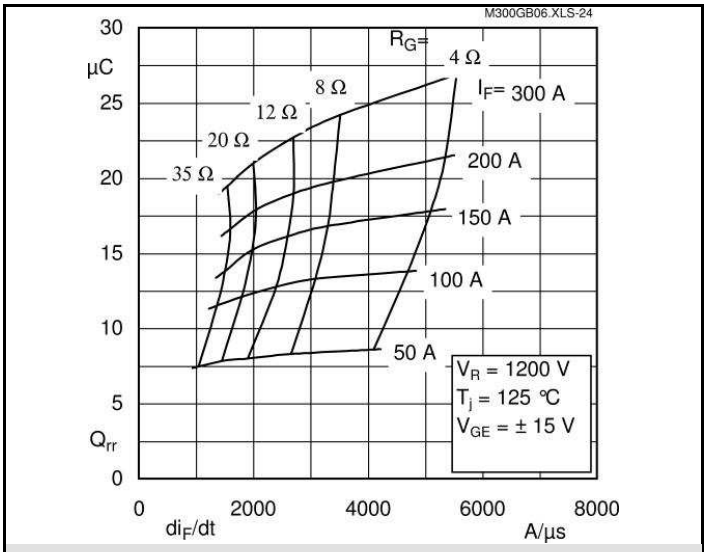
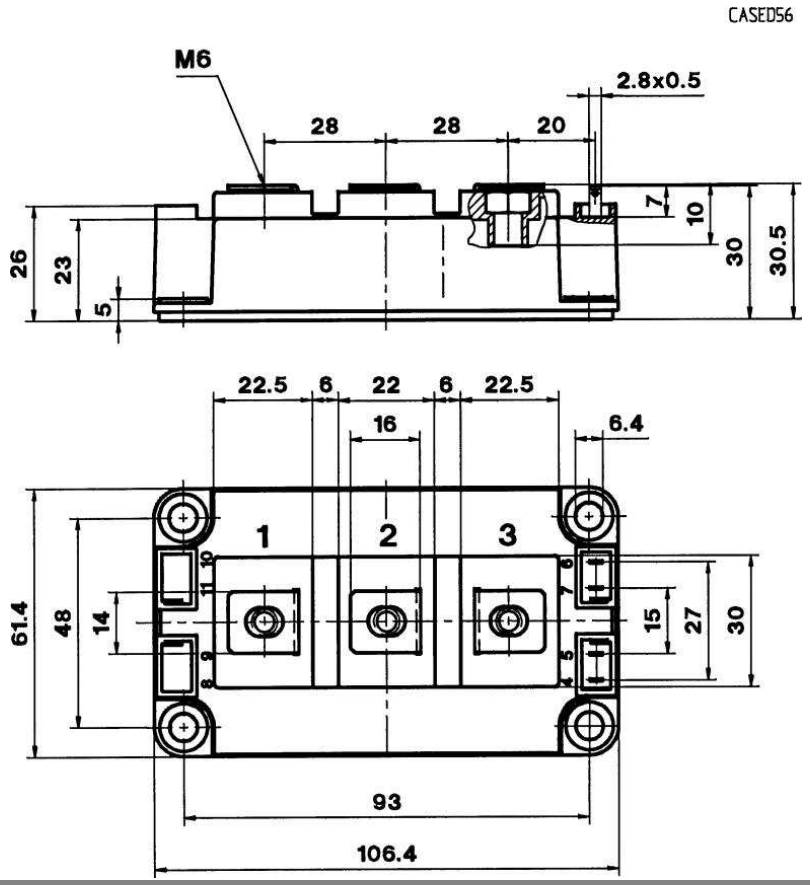


Fig. 12 Typ. CAL diode recovered charge

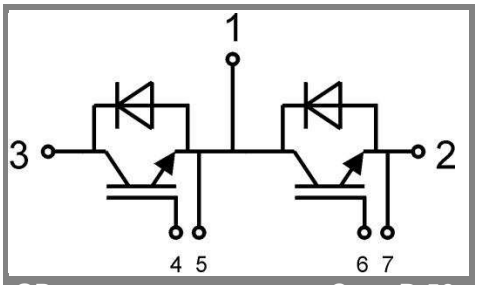
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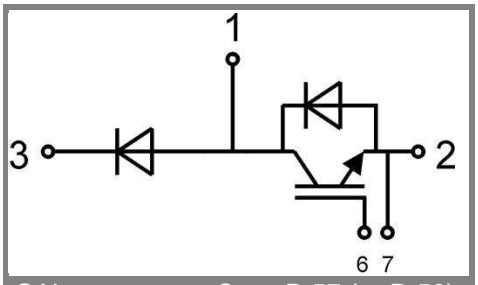
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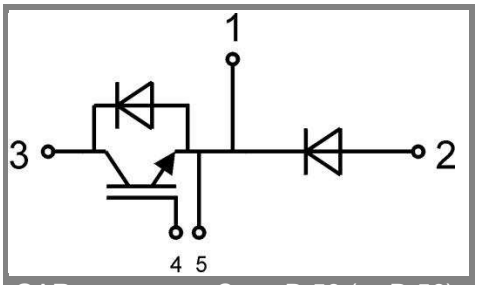
Case D 56



GB Case D 56



GAL Case D 57 (➞ D 56)



GAR Case D 58 (➞ D 56)

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